



Product Change Notification

CN-202606006F

Issue date: 03 Jul 2026

Effective date: 15 Oct 2026

Dear

productchangenotices@premierfarnell.com,

Here's your personalized quality information concerning products our customers and partners purchased from Nexperia.

For more details please contact your respective Nexperia CSR/AM.



Release of SOT363 Package on STS (Strip-to-Strip) Backend Assembly Platform - Wave 1

Change Category

☐ Wafer Fab Process	☒ Assembly Process	☐ Product Marking	☐ Test Location	☐ Design
☐ Wafer Fab Materials	☒ Assembly Materials	☐ Mechanical Specification	☐ Test Process	☐ Errata
☐ Wafer Fab Location	☐ Assembly Location	☐ Packing/Shipping/Labeling	☐ Test Equipment	☐ Electrical spec./Test coverage

Details of this change

The SOT363 package is released on STS (strip-to-strip) backend assembly platform in combination with the following changes:

- Manufacturing based on strip-to-strip concept utilizing same basic technologies
- Release of mold compound EME-G700KC and leadframe base material C19400 (Cu)

- Lead width with relaxed dimension of lower specification limit (but with no change to solder footprint)
- Package version designated as SOT363-3 to reflect updated lead width specification in package outline

CN-202606006F_PCN-FORM.xlsx: https://qcm.nexperia.com/Document/DOC-613515/CN-202606006F_PCN-FORM.xlsx

CN-202606006F_Self-Qualification-Report.pdf:
https://qcm.nexperia.com/Document/DOC-613514/CN-202606006F_Self-Qualification-Report.pdf

CN-202606006F_PCN-Delta-Qualification-Matrix-ZVEI.xlsx:
https://qcm.nexperia.com/Document/DOC-613476/CN-202606006F_PCN-Delta-Qualification-Matrix-ZVEI.xlsx

CN-202606006F_Change-Matrix.xlsx: https://qcm.nexperia.com/Document/DOC-613477/CN-202606006F_Change-Matrix.xlsx

Why do we implement this change?

To enhance manufacturing flexibility, increase throughput, and support future production growth as part of Nexperia's long-term capacity strategy to enable future supply scaling.

Identification of affected products

Product Identification does not change

Changed products can be identified by date code after implementation.

Management summary

SEM-AN-01 - Any change with impact on agreed upon technical contractual agreements (adaptation of datasheet)
SEM-PA-11 - Mold Compound
SEM-PA-02 - Leadframe base material
SEM-PA-03 - Leadframe dimensions
SEM-EQ-02 - Production equipment

Product availability

Production

Planned first shipment: 15 Oct 2026

Existing inventory will be shipped until depleted

Sample information

Samples are available upon request

Impact

No impact to the product's functionality anticipated

Data sheet revision

A new datasheet will be issued

Feedback

Your acknowledgement of this change, conform JEDEC J-STD-046, is expected till 02 Aug 2026. Lack of acknowledgement of the PCN constitutes acceptance of the change.

Additional information

[View Change Notification Online](#)

Contact and support

For all Quality Notification content inquiries, please contact your local Nexperia Sales Support Team.

For specific questions on this notice or the products affected please contact our specialist directly: pcn@nexperia.com

In case of distribution, please contact you distribution partner.

About Nexperia B.V.

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